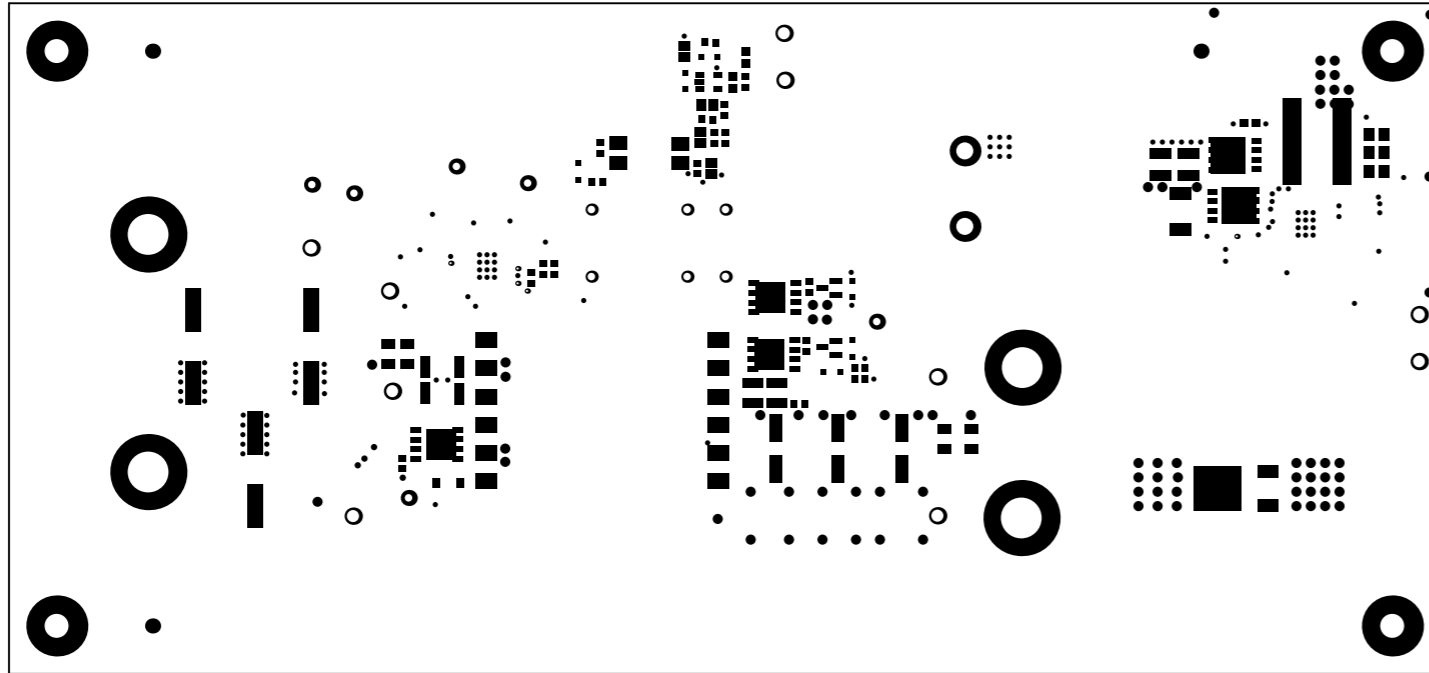
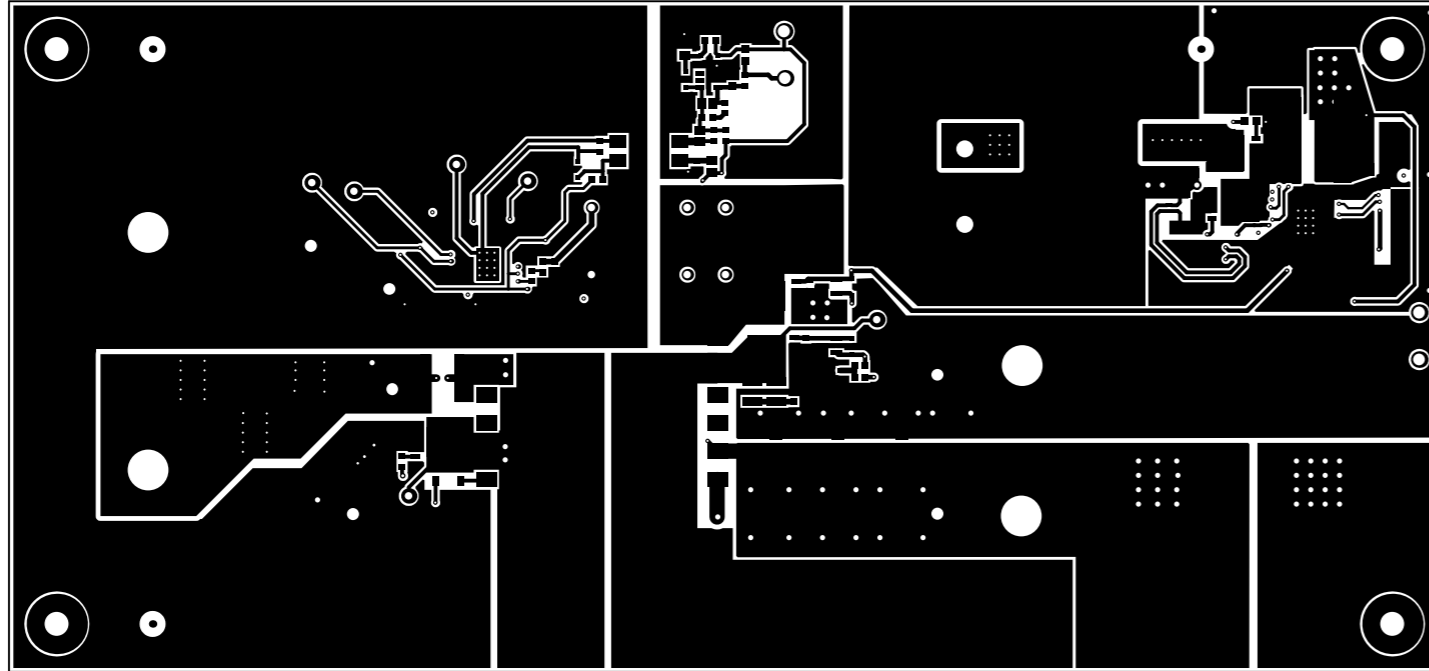


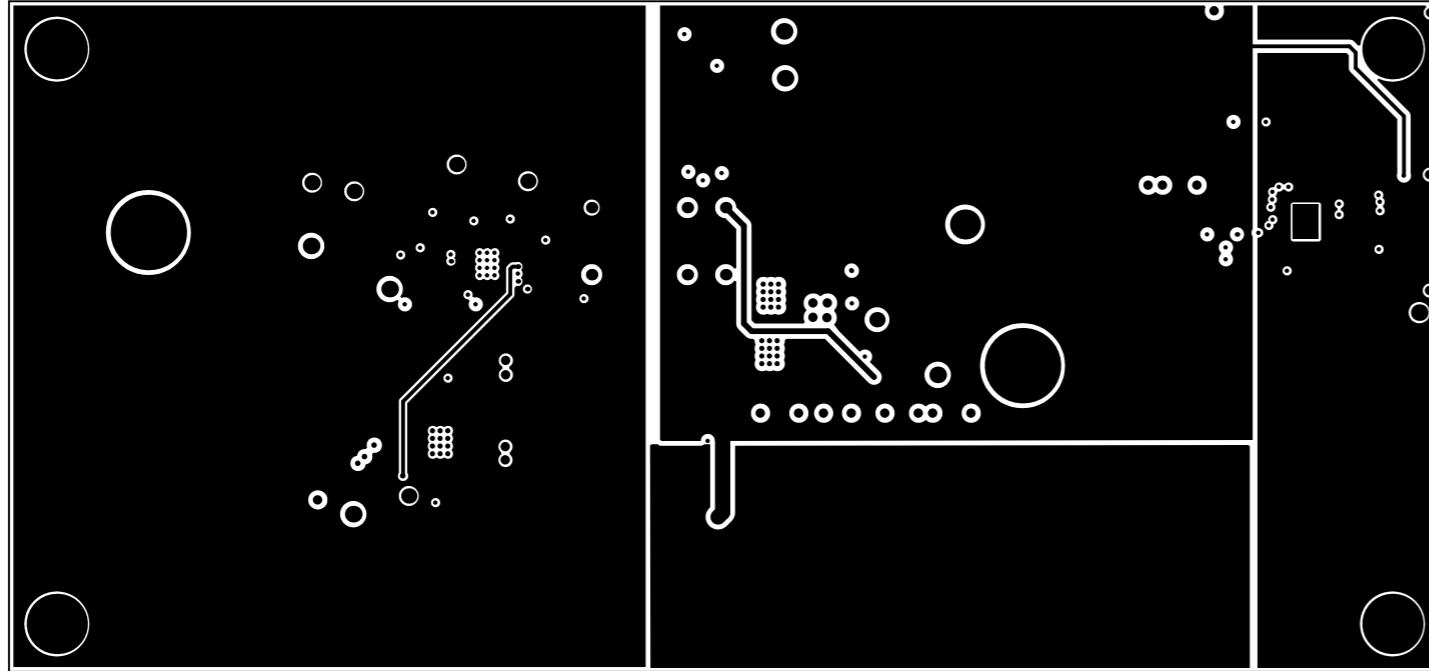
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/15/2014 9:02:30 AM	TEXAS INSTRUMENTS	



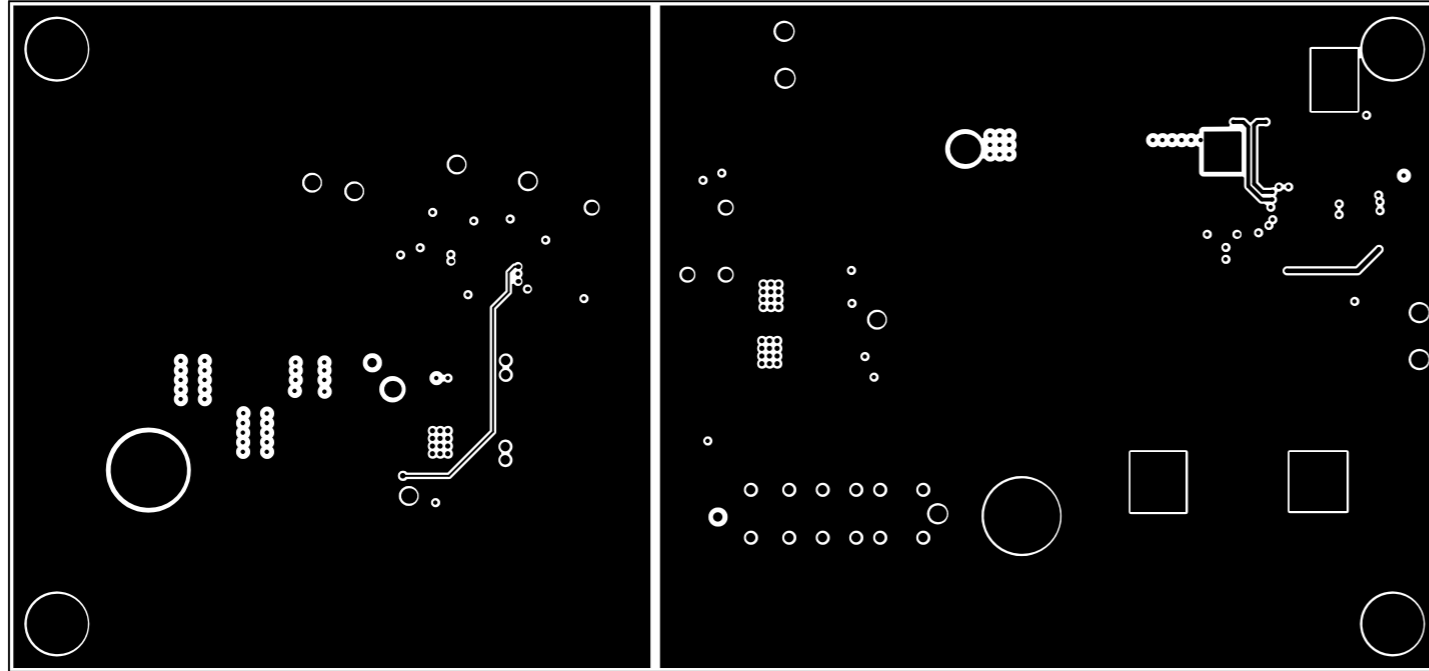
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/15/2014 9:02:30 AM	TEXAS INSTRUMENTS	



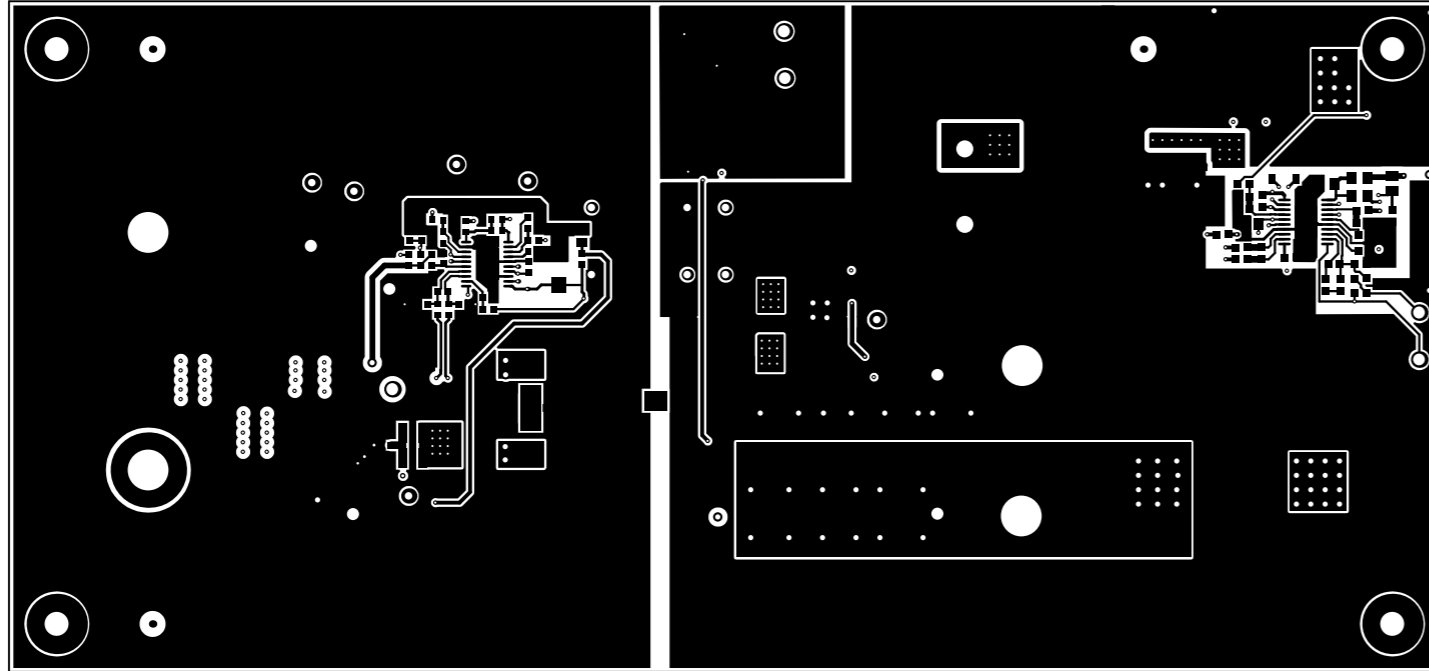
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/15/2014 9:02:31 AM	TEXAS INSTRUMENTS	



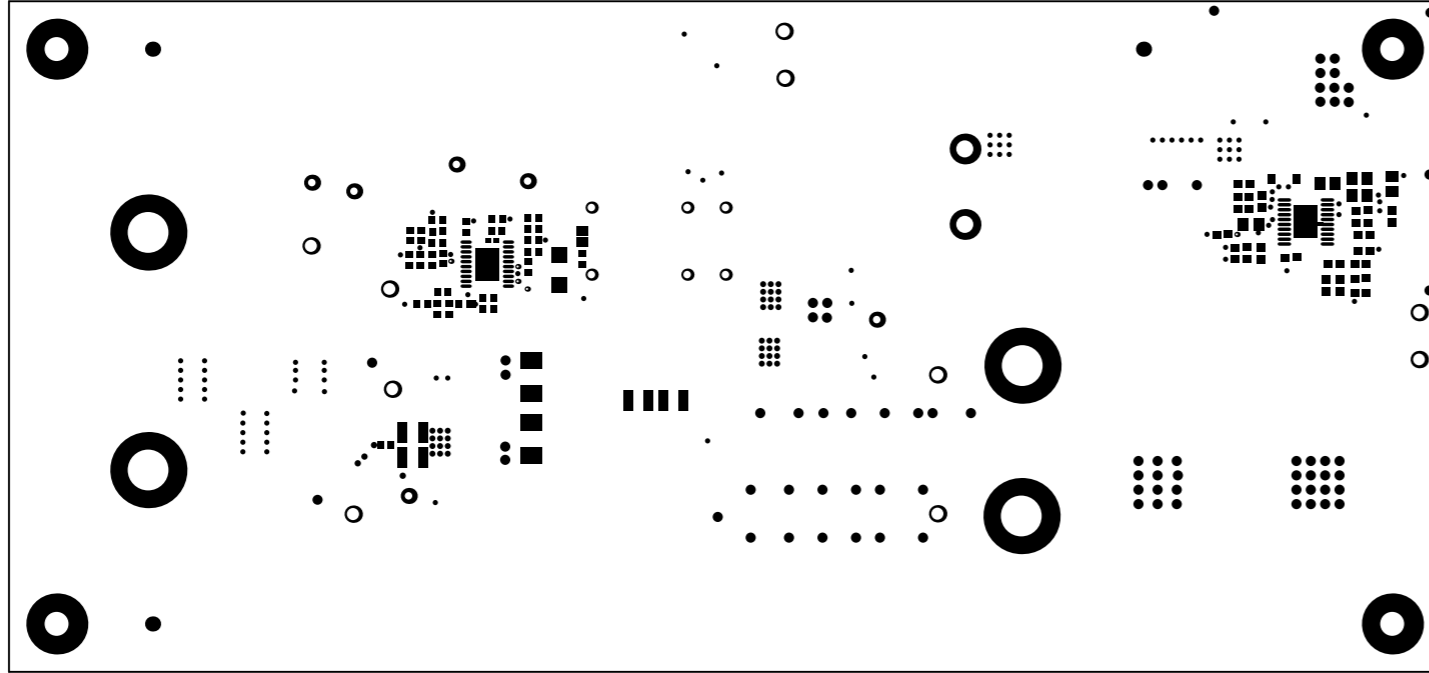
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 1	GENERATED : 10/15/2014 9:02:32 AM	TEXAS INSTRUMENTS	



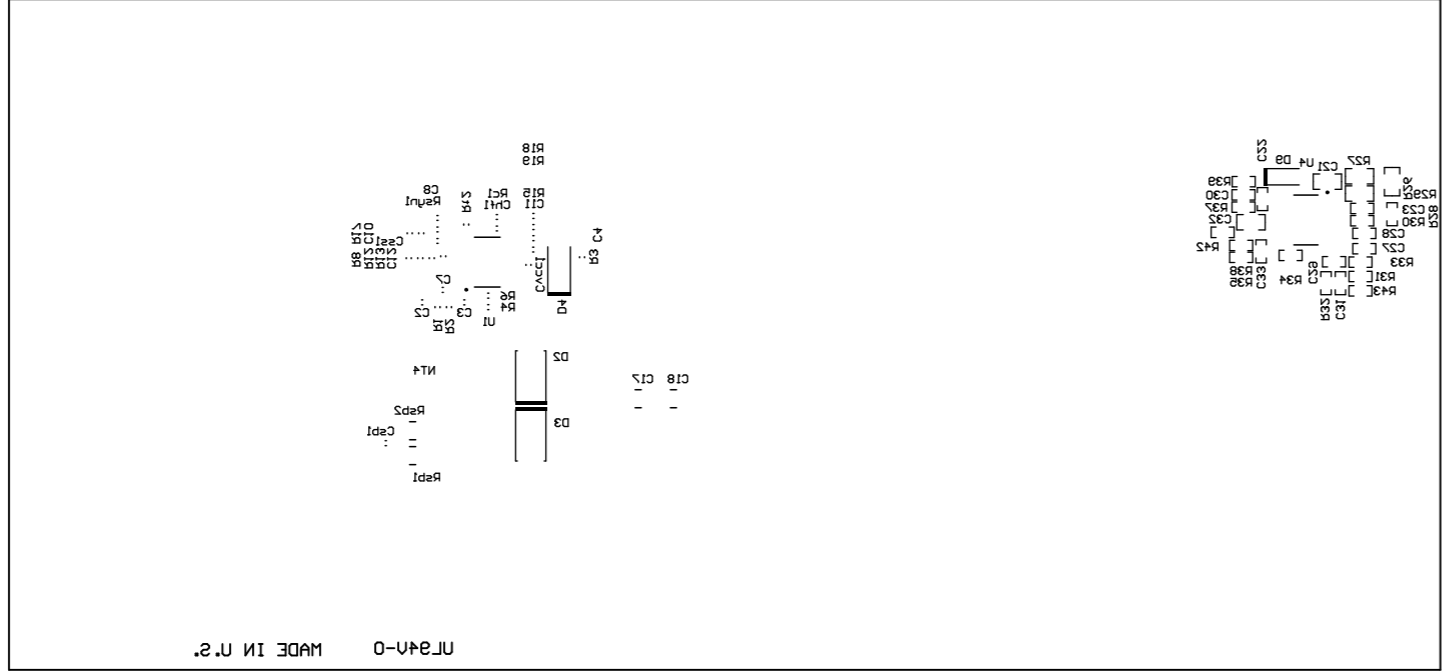
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 2	GENERATED : 10/15/2014 9:02:33 AM	TEXAS INSTRUMENTS	



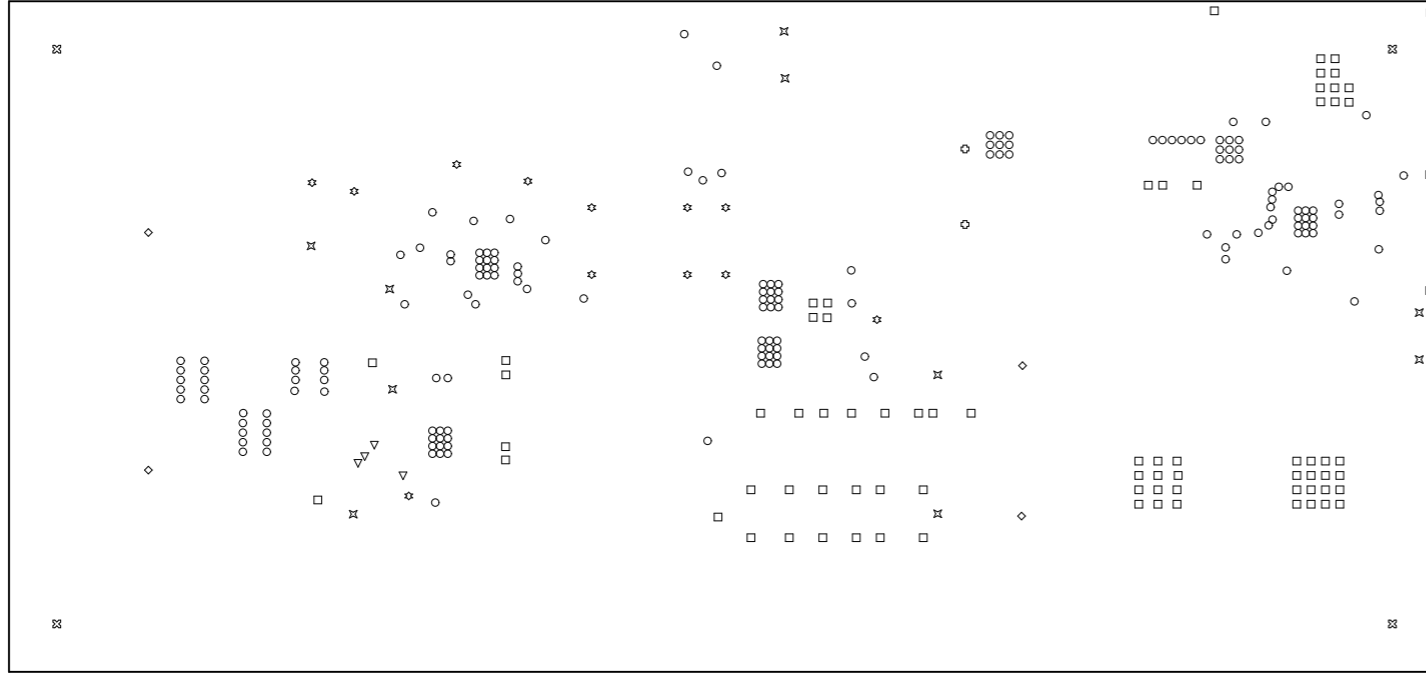
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/15/2014 9:02:33 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/15/2014 9:02:34 AM	TEXAS INSTRUMENTS	



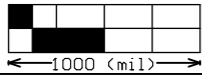
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/15/2014 9:02:35 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	165	12mil (0.305mm)	PTH	Round
▽	4	15mil (0.381mm)	PTH	Round
□	76	28mil (0.711mm)	PTH	Round
*	12	40mil (1.016mm)	PTH	Round
x	10	63mil (1.6mm)	PTH	Round
⊕	2	90.551mil (2.3mm)	PTH	Round
⊗	4	125.984mil (3.2mm)	PTH	Round
◇	4	214.567mil (5.45mm)	PTH	Round
	277	Total		

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/15/2014 9:02:36 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10506	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/15/2014 9:02:36 AM	TEXAS INSTRUMENTS	

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